

CET246 Electronic Design Automation

Printed Circuit Board Anatomy

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Introduction

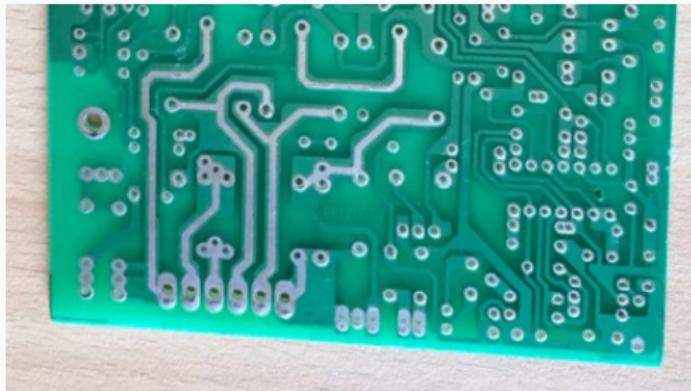
A printed circuit board (PCB):

1. Supports the components physically
2. Connects the components electrically

Electronics have become smaller and more complex leading to the need for precise planning and thorough testing

Electrical Connections

- A “trace” is the equivalent of a wire for conduction electricity
- Power/ground traces tend to be larger
- Signal traces are usually narrower

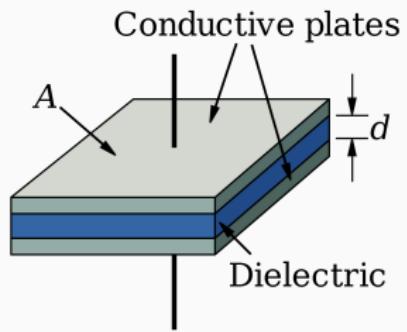


Material Properties

Electrical Properties

Electrical properties include, but are not limited to:

1. Dielectric Constant
2. Dielectric Breakdown Strength
3. Dielectric Strength
4. Arc Resistance



Physical Properties

Physical properties include, but are not limited to:

1. Tensile Strength
2. Compression
3. Shear
4. Flexural Strength
5. Impact Strength
6. Laminating difficulty
7. Copper adhesion
8. Machinability
9. Dimensional Stability

Environmental Properties

Environmental properties include, but are not limited to:

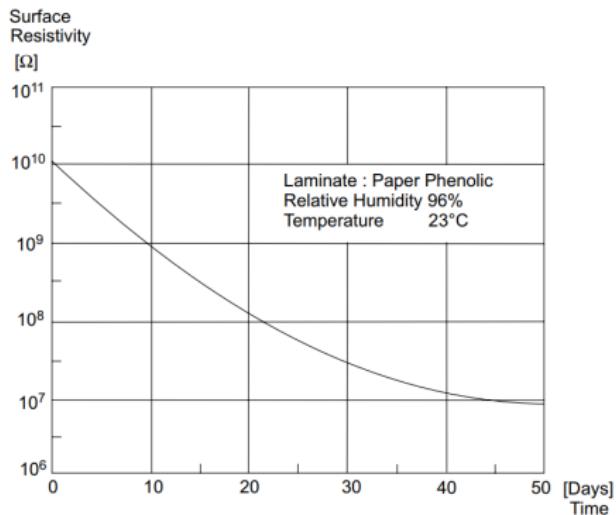
1. Absorption of water
2. Environmental resistance
3. Fungus resistance
4. Flammability
5. Self-extinguishing
6. Heat resistance

Common Materials

Paper Laminate

Resin made of phenol and formaldehyde, reinforced with paper filler

- Easy Fabrication
- Low cost
- Poor arc resistance
- High water absorption



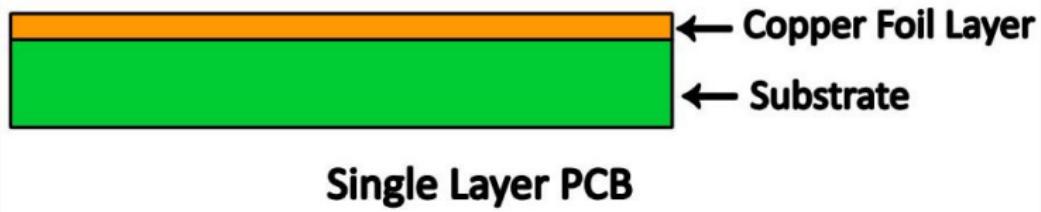
FR4

Reinforced with glass fiber or cloth fiber as filler and epoxy resin

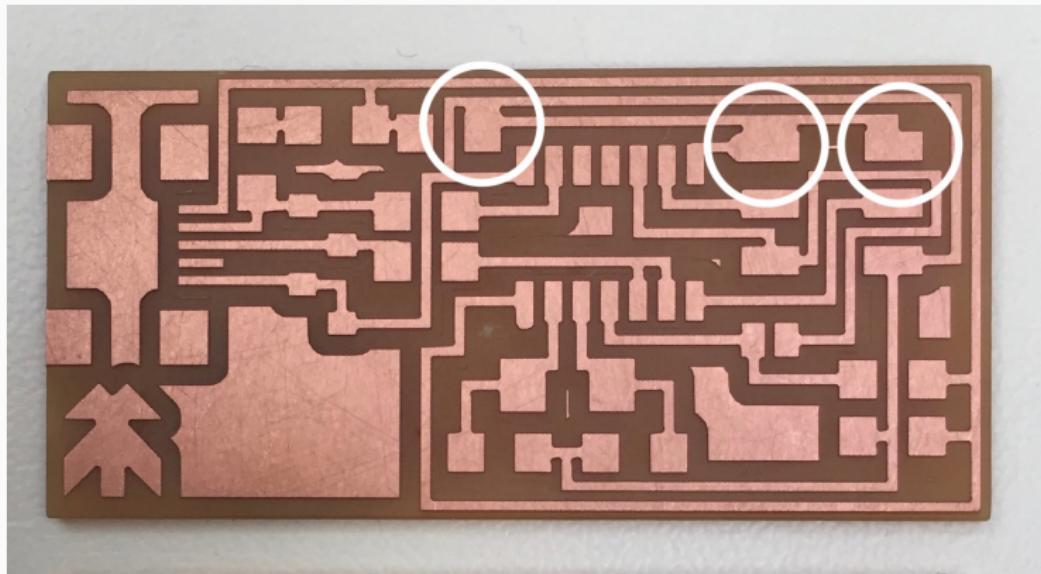
- Good dimensional stability
- Good mechanical strength
- Superior electrical properties
- Low water absorption
- Higher cost

Layers

Single Layer Boards



Single Layer Boards

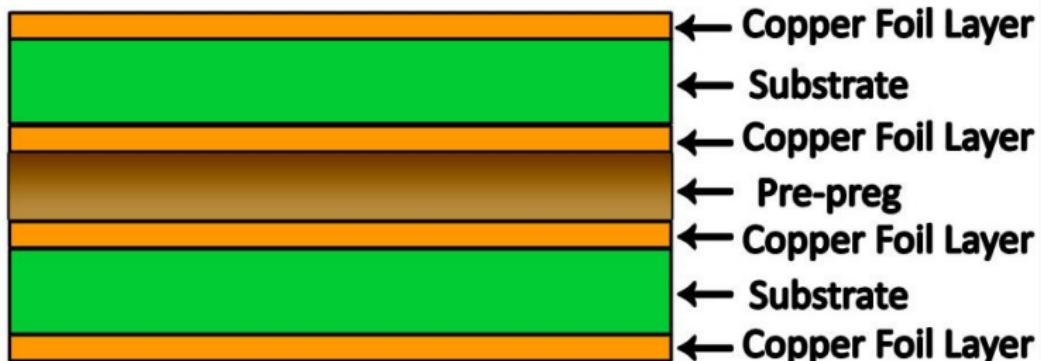


Double Layer Boards

Double Layer PCB



Multi-Layer Boards

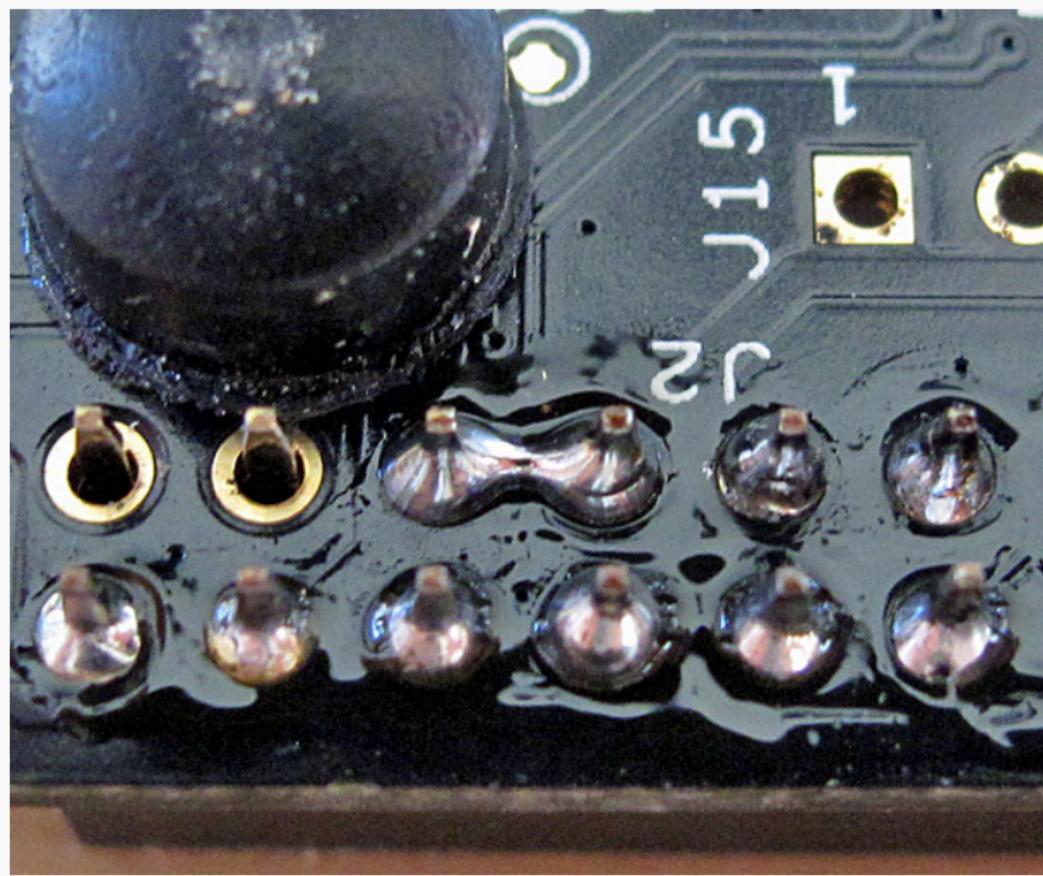


Multilayer PCB

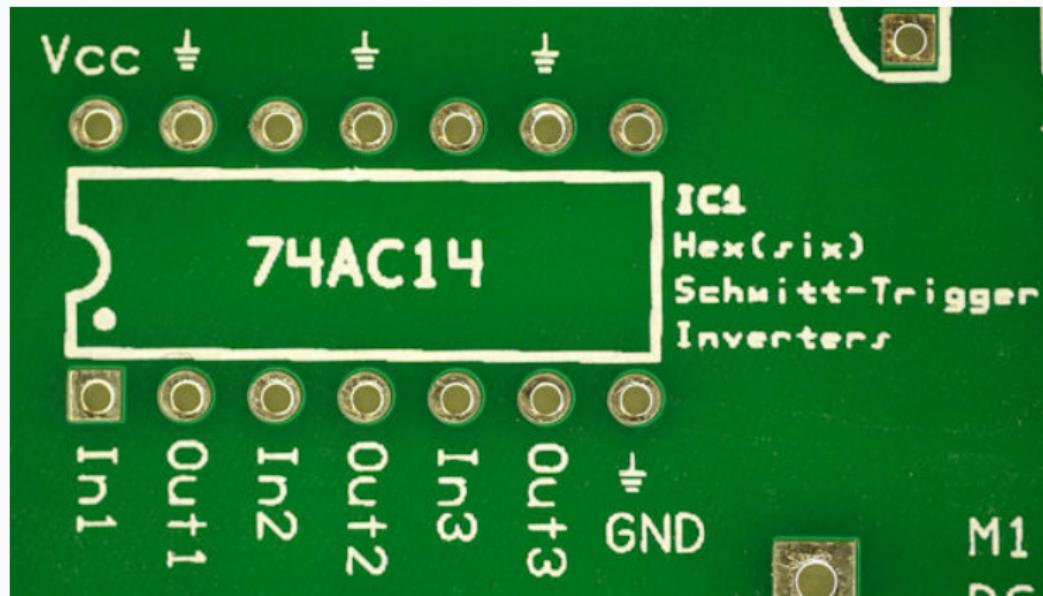
Solder Mask



Solder Mask



Silk Screen



Multi-layer Example

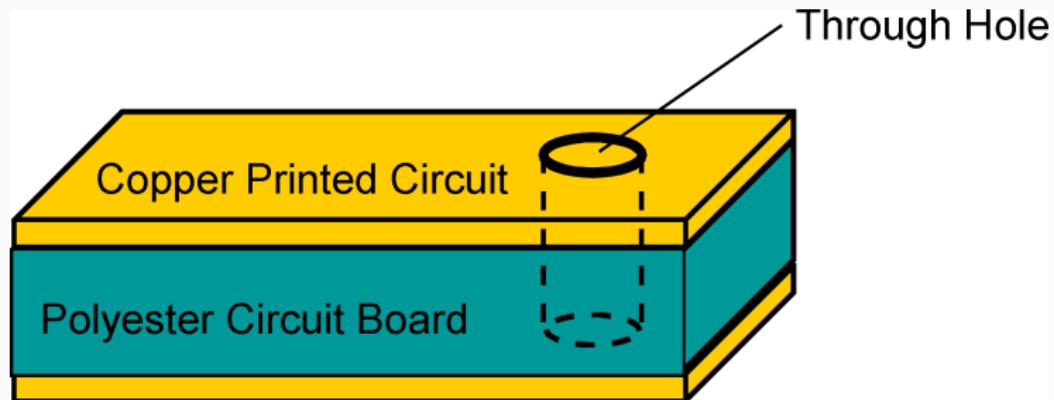


Multi-layer Example

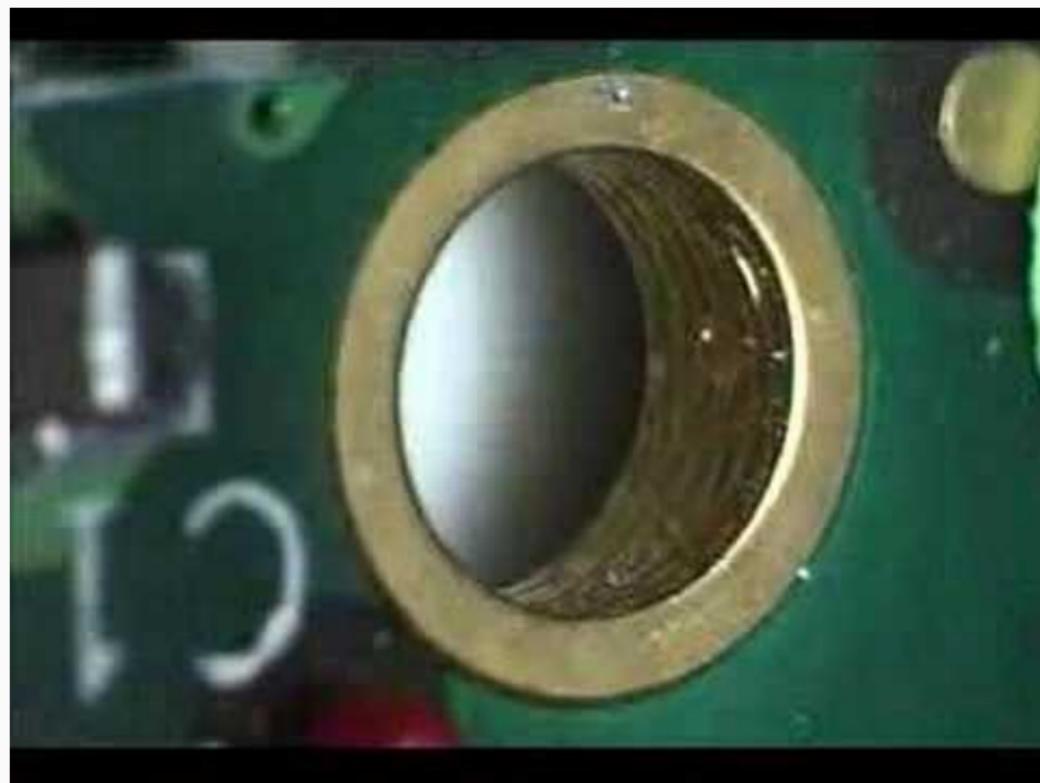
	Soldermask
top layer →	High speed signal layer
	Prepreg
layer 2 →	GND plane
	Prepreg
layer 3 →	High speed signal layer
	Core
layer 4 →	GND plane
	Prepreg
layer 5 →	GND plane
	Core
layer 6 →	High speed signal layer
	Prepreg
layer 7 →	GND plane
	Prepreg
bottom layer →	High speed signal layer
	Soldermask

Mounting Methods

Through-hole



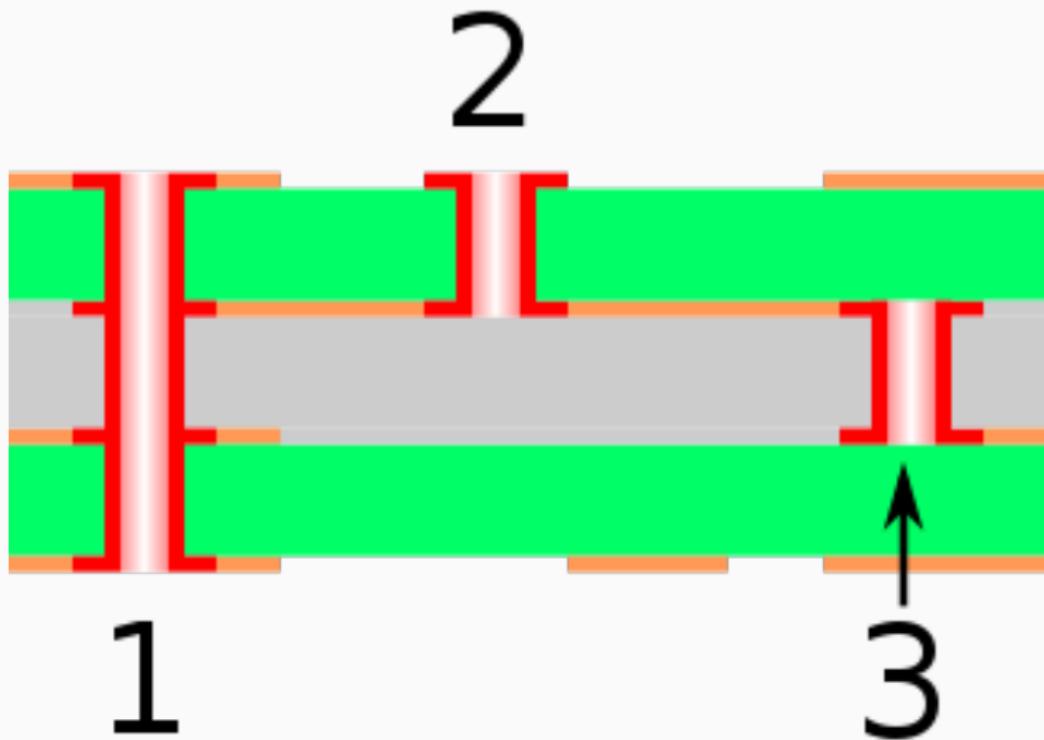
Through-hole Plating



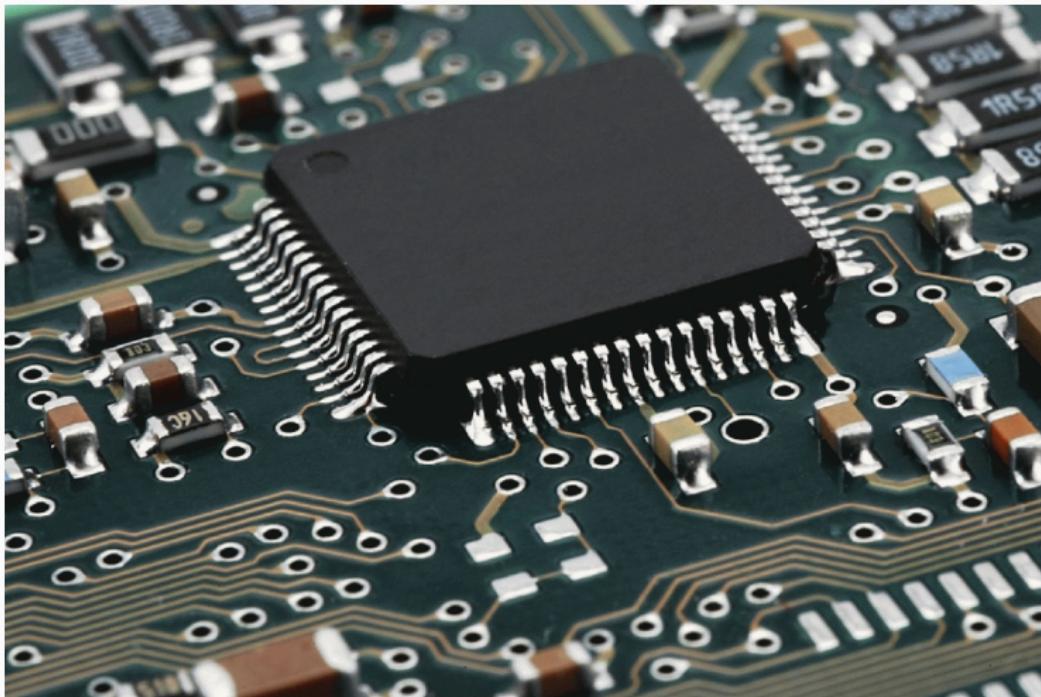
Through-hole Plating



Vias



Surface Mount Technology



SM-Alphabet Soup

1. SMA (surface-mount assembly) a build or module assembled using SMT.
2. SMC (surface-mount components) components for SMT.
3. SMD (surface-mount devices) active, passive, and electromechanical components.
4. SME (surface-mount equipment) machines used for SMT.
5. SMP (surface mount packages) SMD case forms.
6. SMT (surface-technology) the act and method of assembling and mounting electronic technology.

Embedded Components

